



## **Benefits of Occam Process Electronic Assemblies (Summary)**

The Occam Process is a new technology for making electronics assemblies (mother boards and modules). Occam Process offers benefits for consumer, commercial and military/aerospace markets.

### **Lead Free benefits of Occam Process assembly:**

- 1) Completely Lead Free (RoHS) Green
- 2) No use of solder
- 3) No use of solder paste
- 4) No heating (because no need to melt solder)
- 5) Because no heat, it means much reduced component failure during assembly

### **Additional benefits of Occam Process assembly:**

- 6) Assembly is fully molded
- 7) Very rugged construction - Able to drop and throw
- 8) Water proof (because it is fully molded)
- 9) Lower cost production (compared to normal PC Board construction)
- 10) Smaller, because components positioned overlapping each other on multi-layers

### **Test Vehicle:**

Early stage development of Occam Process requires building test vehicles to fully understand design rules, production methods and techniques.

TopLine offers test vehicle components with daisy chain so that customers can practice making Occam Process assemblies.

---

Test Vehicle Components available from:

**TopLine**<sup>®</sup>

**Tel (800) 776-9888**

Email: [info@topline.tv](mailto:info@topline.tv)

[www.verdant-tv.com](http://www.verdant-tv.com)